



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-11-29
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana SAN BIAGIO	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	B5V2*L756CA6	A	BO2A	2017-11-29
Amount	UoM	Unit type	ST ECOPACK Grade	
5700.00	mg	Each	ECOPACK® 1	
	Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SVP	20x10.7x4.5	15	Through-hole	
Comment	Package: V2 MULTIWATT 15L SPLIT VERT.; MDF valid for L296P			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	B5V2*U756CA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	10.224	mg	supplier	die	Silicon (Si)	7440-21-3		9.927	mg	970951	1742
				supplier	metallization	Aluminium (Al)	7429-90-5		0.126	mg	12324	22
				supplier	Passivation	Silicon Nitride	12033-89-5		0.043	mg	4206	8
				supplier	Passivation	Silicon Oxide	7631-86-9		0.058	mg	5673	10
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.008	mg	782	1
				supplier	back side metallization	Gold (Au)	7440-57-5		0.021	mg	2054	4
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.039	mg	3815	7
Leadframe	Copper & its alloys	4799.845	mg	supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	196	0
				supplier	alloy	Copper (Cu)	7440-50-8		4789.257	mg	997794	840221
				supplier	alloy	Iron (Fe)	7439-89-6		2.206	mg	460	387
Soft solder	Other inorganic materials	9.579	mg	supplier	alloy	Iron Phosphide (FeP)	26508-33-8		4.028	mg	839	707
				supplier	metallization	Silver (Ag)	7440-22-4		4.354	mg	907	764
				supplier	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	9.339	mg	974945	1638
				supplier	solder	Silver (Ag)	7440-22-4		0.144	mg	15033	25
Bonding wires	Other inorganic materials	0.761	mg	supplier	solder	Tin (Sn)	7440-31-5		0.096	mg	10022	17
				supplier	wire	Copper (Cu)	7440-50-8		0.863	mg	1000000	151
Encapsulation	Other Organic Materials	848.445	mg	supplier	mold compound	Silica, vitreous	60676-86-0		608.335	mg	717000	106725
				supplier	mold compound	Epoxy Cresol Novelak	29690-82-2		144.236	mg	170000	25305
				supplier	mold compound	Phenol resin	9003-35-4		61.088	mg	72000	10717
				supplier	mold compound	Brominated epoxy resin	40039-93-8		12.727	mg	15000	2233
				supplier	mold compound	Antimony Trioxide	1309-64-4		16.969	mg	20000	2977
				supplier	mold compound	Bismuth	7440-69-9		2.545	mg	3000	446
connections coating	Solder	31.044	mg	supplier	mold compound	Carbon black	1333-86-4		2.545	mg	3000	446
				supplier	solder alloy	Tin (Sn)	7440-31-5		31.044	mg	1000000	5446